

74LVC1G175

Single D-type flip-flop with reset; positive-edge trigger

Rev. 01 — 18 October 2004

Product data sheet

1. General description

The 74LVC1G175 is a high-performance, low-voltage, Si-gate CMOS device, superior to most advanced CMOS compatible TTL families.

The input can be driven from either 3.3 V or 5 V devices. This feature allows the use of this device in a mixed 3.3 V and 5 V environment.

This device is fully specified for partial power-down applications using I_{off} . The I_{off} circuitry disables the output, preventing the damaging backflow current through the device when it is powered down.

The 74LVC1G175 is a single positive edge triggered D-type flip-flop with individual data (D) input, clock (CP) input, master reset (\overline{MR}) input, and Q output.

The master reset (\overline{MR}) is an asynchronous active LOW input and operate independently of the clock input. Information on the data input is transferred to the Q output on the LOW-to-HIGH transition of the clock pulse. The D input must be stable one set-up time prior to the LOW-to-HIGH clock transition, for predictable operation.

Schmitt-trigger action at all inputs makes the circuit highly tolerant to slower input rise and fall times.

2. Features

- Wide supply voltage range from 1.65 V to 5.5 V
- 5 V tolerant inputs for interfacing with 5 V logic
- High noise immunity
- Complies with JEDEC standard:
 - ◆ JESD8-7 (1.65 V to 1.95 V)
 - ◆ JESD8-5 (2.3 V to 2.7 V)
 - ◆ JESD8B/JESD36 (2.7 V to 3.6 V).
- ± 24 mA output drive ($V_{CC} = 3.0$ V)
- ESD protection:
 - ◆ HBM EIA/JESD22-A114-B exceeds 2000 V
 - ◆ MM EIA/JESD22-A115-A exceeds 200 V.
- CMOS low power consumption
- Latch-up performance exceeds 250 mA
- Direct interface with TTL levels
- Inputs accept voltages up to 5 V
- Multiple package options
- Specified from -40 °C to $+85$ °C and -40 °C to $+125$ °C.

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3. Quick reference data

Table 1: Quick reference data

$GND = 0\text{ V}$; $T_{amb} = 25\text{ °C}$; $t_r = t_f \leq 2.5\text{ ns}$.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
t_{PHL} , t_{PLH}	propagation delay CP to Q	$C_L = 50\text{ pF}$; $V_{CC} = 3.3\text{ V}$	1.0	3.1	5.7	ns
	propagation delay MR to Q	$C_L = 50\text{ pF}$; $V_{CC} = 3.3\text{ V}$	1.0	2.5	5.8	ns
f_{max}	maximum clock frequency	$C_L = 50\text{ pF}$; $V_{CC} = 3.3\text{ V}$	175	300	-	MHz
C_I	input capacitance		-	2.5	-	pF
C_{PD}	power dissipation capacitance	$V_{CC} = 3.3\text{ V}$	[1][2]	14	-	pF

[1] C_{PD} is used to determine the dynamic power dissipation (P_D in μW).

$$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma(C_L \times V_{CC}^2 \times f_o) \text{ where:}$$

f_i = input frequency in MHz;

f_o = output frequency in MHz;

C_L = output load capacitance in pF;

V_{CC} = supply voltage in Volts;

N = number of inputs switching;

$\Sigma(C_L \times V_{CC}^2 \times f_o)$ = sum of the outputs.

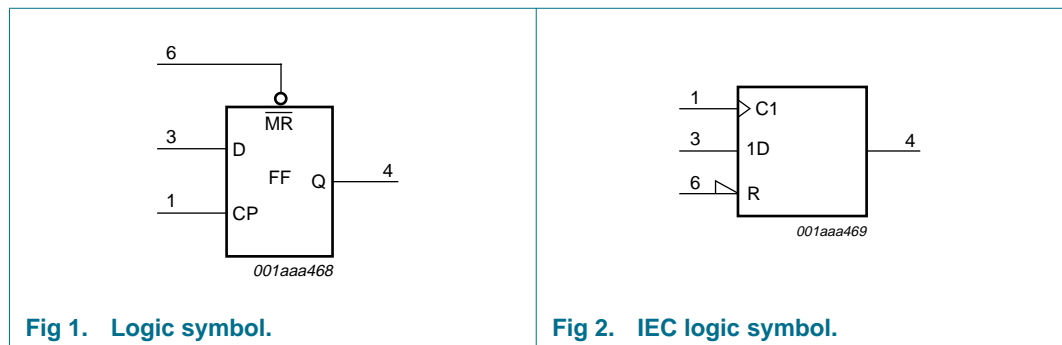
[2] The condition is $V_I = GND$ to V_{CC} .

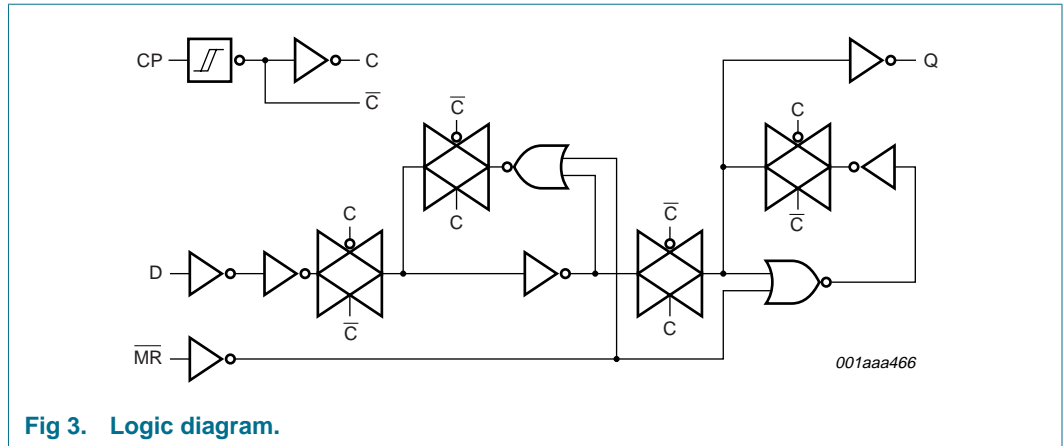
4. Ordering information

Table 2: Ordering information

Type number	Package			Version
	Temperature range	Name	Description	
74LVC1G175GW	-40 °C to +125 °C	SC-88	plastic surface mounted package; 6 leads	SOT363
74LVC1G175GV	-40 °C to +125 °C	SC-74	plastic surface mounted package; 6 leads	SOT457
74LVC1G175GM	-40 °C to +125 °C	XSON6	plastic extremely thin small outline package; no leads; 6 terminals; body 1 × 1.45 × 0.5 mm	SOT886

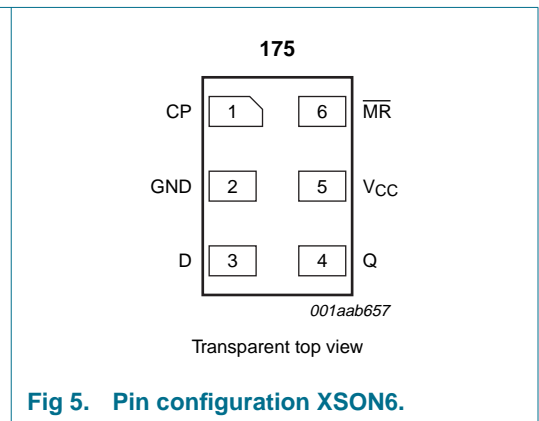
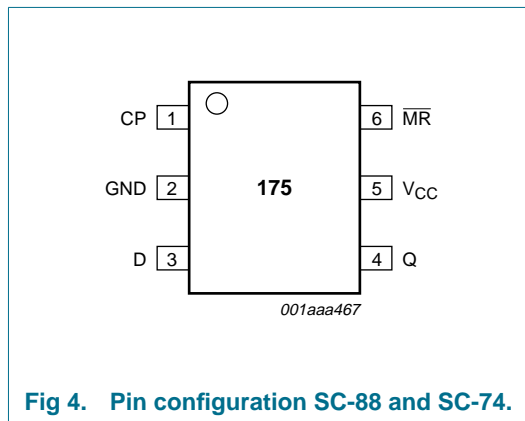
5. Functional diagram





6. Pinning information

6.1 Pinning



6.2 Pin description

Table 3: Pin description

Symbol	Pin	Description
CP	1	clock input (LOW-to-HIGH, edge-triggered)
GND	2	ground (0 V)
D	3	data input
Q	4	flip-flop output
V _{CC}	5	supply voltage
MR	6	master reset input (active LOW)

7. Functional description

7.1 Function table

Table 4: Function table [1]

Operating mode	Input			Output
	MR	CP	D	Q
Reset (clear)	L	X	X	L
Load '1'	H	↑	h	H
Load '0'	H	↑	l	L

- [1] H = HIGH voltage level;
 h = HIGH voltage level one set-up time prior to the LOW-to-HIGH CP transition;
 L = LOW voltage level;
 l = LOW voltage level one set-up time prior to the LOW-to-HIGH CP transition;
 ↑ = LOW-to-HIGH CP transition;
 X = don't care.

8. Limiting values

Table 5: Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CC}	supply voltage		-0.5	+6.5	V
I_{IK}	input diode current	$V_I < 0$ V	-	-50	mA
V_I	input voltage		[1] -0.5	+6.5	V
I_{OK}	output diode current	$V_O > V_{CC}$ or $V_O < 0$ V	-	±50	mA
V_O	output voltage	active mode	[1][2] -0.5	$V_{CC} + 0.5$	V
		Power-down mode	[1][2] -0.5	+6.5	V
I_O	output diode current	$V_O = 0$ V to V_{CC}	-	±50	mA
I_{CC}, I_{GND}	V_{CC} or GND current		-	±100	mA
T_{stg}	storage temperature		-65	+150	°C
P_{tot}	power dissipation	$T_{amb} = -40$ °C to +125 °C	-	250	mW

- [1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
 [2] When $V_{CC} = 0$ V (Power-down mode), the output voltage can be 5.5 V in normal operation.

9. Recommended operating conditions

Table 6: Recommended operating conditions

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CC}	supply voltage		1.65	5.5	V
V_I	input voltage		0	5.5	V
V_O	output voltage	active mode	0	V_{CC}	V
		Power-down mode; $V_{CC} = 0$ V	0	5.5	V

Table 6: Recommended operating conditions ...continued

Symbol	Parameter	Conditions	Min	Max	Unit
T_{amb}	ambient temperature		-40	+125	°C
t_r, t_f	input rise and fall times	$V_{CC} = 1.65 \text{ V to } 2.7 \text{ V}$	0	20	ns/V
		$V_{CC} = 2.7 \text{ V to } 5.5 \text{ V}$	0	10	ns/V

10. Static characteristics

Table 7: Static characteristics

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$T_{amb} = -40 \text{ °C to } +85 \text{ °C [1]}$						
V_{IH}	HIGH-level input voltage	$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$	$0.65 \times V_{CC}$	-	-	V
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.7	-	-	V
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	2.0	-	-	V
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	$0.7 \times V_{CC}$	-	-	V
V_{IL}	LOW-level input voltage	$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$	-	-	$0.35 \times V_{CC}$	V
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	-	-	0.7	V
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	-	-	0.8	V
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	-	-	$0.3 \times V_{CC}$	V
V_{OH}	HIGH-level output voltage	$V_I = V_{IH} \text{ or } V_{IL}$				
		$I_O = -100 \text{ } \mu\text{A}; V_{CC} = 1.65 \text{ V to } 5.5 \text{ V}$	$V_{CC} - 0.1$	-	-	V
		$I_O = -4 \text{ mA}; V_{CC} = 1.65 \text{ V}$	1.2	1.54	-	V
		$I_O = -8 \text{ mA}; V_{CC} = 2.3 \text{ V}$	1.9	2.15	-	V
		$I_O = -12 \text{ mA}; V_{CC} = 2.7 \text{ V}$	2.2	2.50	-	V
		$I_O = -24 \text{ mA}; V_{CC} = 3.0 \text{ V}$	2.3	2.62	-	V
V_{OL}	LOW-level output voltage	$V_I = V_{IH} \text{ or } V_{IL}$				
		$I_O = 100 \text{ } \mu\text{A}; V_{CC} = 1.65 \text{ V to } 5.5 \text{ V}$	-	-	0.10	V
		$I_O = 4 \text{ mA}; V_{CC} = 1.65 \text{ V}$	-	0.07	0.45	V
		$I_O = 8 \text{ mA}; V_{CC} = 2.3 \text{ V}$	-	0.12	0.30	V
		$I_O = 12 \text{ mA}; V_{CC} = 2.7 \text{ V}$	-	0.17	0.40	V
		$I_O = 24 \text{ mA}; V_{CC} = 3.0 \text{ V}$	-	0.33	0.55	V
	$I_O = 32 \text{ mA}; V_{CC} = 4.5 \text{ V}$	-	0.39	0.55	V	
I_{LI}	input leakage current	$V_I = 5.5 \text{ V or GND}; V_{CC} = 5.5 \text{ V}$	-	± 0.1	± 5	μA
I_{off}	power OFF leakage current	$V_I \text{ or } V_O = 5.5 \text{ V}; V_{CC} = 0 \text{ V}$	-	± 0.1	± 10	μA
I_{CC}	quiescent supply current	$V_I = V_{CC} \text{ or GND}; I_O = 0 \text{ A}; V_{CC} = 5.5 \text{ V}$	-	0.1	10	μA
ΔI_{CC}	additional quiescent supply current per pin	$V_I = V_{CC} - 0.6 \text{ V}; I_O = 0 \text{ A}; V_{CC} = 2.3 \text{ V to } 5.5 \text{ V}$	-	5	500	μA
C_I	input capacitance		-	2.5	-	pF

Table 7: Static characteristics ...continued

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
T_{amb} = -40 °C to +125 °C						
V _{IH}	HIGH-level input voltage	V _{CC} = 1.65 V to 1.95 V	0.65 × V _{CC}	-	-	V
		V _{CC} = 2.3 V to 2.7 V	1.7	-	-	V
		V _{CC} = 2.7 V to 3.6 V	2.0	-	-	V
		V _{CC} = 4.5 V to 5.5 V	0.7 × V _{CC}	-	-	V
V _{IL}	LOW-level input voltage	V _{CC} = 1.65 V to 1.95 V	-	-	0.35 × V _{CC}	V
		V _{CC} = 2.3 V to 2.7 V	-	-	0.7	V
		V _{CC} = 2.7 V to 3.6 V	-	-	0.8	V
		V _{CC} = 4.5 V to 5.5 V	-	-	0.3 × V _{CC}	V
V _{OH}	HIGH-level output voltage	V _I = V _{IH} or V _{IL}				
		I _O = -100 μA; V _{CC} = 1.65 V to 5.5 V	V _{CC} - 0.1	-	-	V
		I _O = -4 mA; V _{CC} = 1.65 V	0.95	-	-	V
		I _O = -8 mA; V _{CC} = 2.3 V	1.7	-	-	V
		I _O = -12 mA; V _{CC} = 2.7 V	1.9	-	-	V
		I _O = -24 mA; V _{CC} = 3.0 V	2.0	-	-	V
V _{OL}	LOW-level output voltage	V _I = V _{IH} or V _{IL}				
		I _O = 100 μA; V _{CC} = 1.65 V to 5.5 V	-	-	0.10	V
		I _O = 4 mA; V _{CC} = 1.65 V	-	-	0.70	V
		I _O = 8 mA; V _{CC} = 2.3 V	-	-	0.45	V
		I _O = 12 mA; V _{CC} = 2.7 V	-	-	0.60	V
		I _O = 24 mA; V _{CC} = 3.0 V	-	-	0.80	V
I _{LI}	input leakage current	V _I = 5.5 V or GND; V _{CC} = 5.5 V	-	-	±20	μA
		I _{off}	power OFF leakage current	V _I or V _O = 5.5 V; V _{CC} = 0 V	-	-
I _{CC}	quiescent supply current	V _I = V _{CC} or GND; I _O = 0 A; V _{CC} = 5.5 V	-	-	40	μA
ΔI _{CC}	additional quiescent supply current per pin	V _I = V _{CC} - 0.6 V; I _O = 0 A; V _{CC} = 2.3 V to 5.5 V	-	-	5000	μA

[1] All typical values are measured at T_{amb} = 25 °C.

11. Dynamic characteristics

Table 8: Dynamic characteristics

$GND = 0 V$; see [Figure 8](#)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
$T_{amb} = -40\text{ }^{\circ}\text{C to }+85\text{ }^{\circ}\text{C}$ [1]							
t_{PHL}, t_{PLH}	propagation delay CP to Q	see Figure 6					
		$V_{CC} = 1.65\text{ V to }1.95\text{ V}$	1.5	4.9	13.4	ns	
		$V_{CC} = 2.3\text{ V to }2.7\text{ V}$	1.0	3.1	7.1	ns	
		$V_{CC} = 2.7\text{ V}$	1.0	3.2	7.1	ns	
		$V_{CC} = 3.0\text{ V to }3.6\text{ V}$	[2] 1.0	3.1	5.7	ns	
		$V_{CC} = 4.5\text{ V to }5.5\text{ V}$	1.0	2.2	4.0	ns	
	propagation delay \overline{MR} to Q	see Figure 7					
		$V_{CC} = 1.65\text{ V to }1.95\text{ V}$	1.5	4.3	12.9	ns	
		$V_{CC} = 2.3\text{ V to }2.7\text{ V}$	1.0	2.8	7.0	ns	
		$V_{CC} = 2.7\text{ V}$	1.0	3.0	7.0	ns	
$V_{CC} = 3.0\text{ V to }3.6\text{ V}$		[2] 1.0	2.5	5.8	ns		
	$V_{CC} = 4.5\text{ V to }5.5\text{ V}$	1.0	2.0	4.1	ns		
t_w	clock pulse width HIGH or LOW	see Figure 6					
		$V_{CC} = 1.65\text{ V to }1.95\text{ V}$	6.2	-	-	ns	
		$V_{CC} = 2.3\text{ V to }2.7\text{ V}$	2.7	-	-	ns	
		$V_{CC} = 2.7\text{ V}$	2.7	-	-	ns	
		$V_{CC} = 3.0\text{ V to }3.6\text{ V}$	[2] 2.7	1.3	-	ns	
		$V_{CC} = 4.5\text{ V to }5.5\text{ V}$	2.0	-	-	ns	
	master reset pulse width LOW	see Figure 7					
		$V_{CC} = 1.65\text{ V to }1.95\text{ V}$	6.2	-	-	ns	
		$V_{CC} = 2.3\text{ V to }2.7\text{ V}$	2.7	-	-	ns	
		$V_{CC} = 2.7\text{ V}$	2.7	-	-	ns	
$V_{CC} = 3.0\text{ V to }3.6\text{ V}$		[2] 2.7	1.6	-	ns		
	$V_{CC} = 4.5\text{ V to }5.5\text{ V}$	2.0	-	-	ns		
t_{rem}	removal time master reset	see Figure 7					
		$V_{CC} = 1.65\text{ V to }1.95\text{ V}$	1.9	-	-	ns	
		$V_{CC} = 2.3\text{ V to }2.7\text{ V}$	1.4	-	-	ns	
		$V_{CC} = 2.7\text{ V}$	1.3	-	-	ns	
		$V_{CC} = 3.0\text{ V to }3.6\text{ V}$	[2] 1.2	0.4	-	ns	
	$V_{CC} = 4.5\text{ V to }5.5\text{ V}$	1.0	-	-	ns		
t_{su}	set-up time D to CP	see Figure 6					
		$V_{CC} = 1.65\text{ V to }1.95\text{ V}$	2.9	-	-	ns	
		$V_{CC} = 2.3\text{ V to }2.7\text{ V}$	1.7	-	-	ns	
		$V_{CC} = 2.7\text{ V}$	1.7	-	-	ns	
		$V_{CC} = 3.0\text{ V to }3.6\text{ V}$	[2] 1.3	0.5	-	ns	
	$V_{CC} = 4.5\text{ V to }5.5\text{ V}$	1.1	-	-	ns		

Table 8: Dynamic characteristics ...continued

GND = 0 V; see [Figure 8](#)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
t _h	hold time D to CP	see Figure 6					
		V _{CC} = 1.65 V to 1.95 V	0.0	-	-	ns	
		V _{CC} = 2.3 V to 2.7 V	0.3	-	-	ns	
		V _{CC} = 2.7 V	0.5	-	-	ns	
		V _{CC} = 3.0 V to 3.6 V	[2] 1.2	0.2	-	ns	
		V _{CC} = 4.5 V to 5.5 V	0.5	-	-	ns	
f _{max}	maximum clock pulse frequency	see Figure 6					
		V _{CC} = 1.65 V to 1.95 V	80	125	-	MHz	
		V _{CC} = 2.3 V to 2.7 V	175	-	-	MHz	
		V _{CC} = 2.7 V	175	-	-	MHz	
		V _{CC} = 3.0 V to 3.6 V	[2] 175	300	-	MHz	
		V _{CC} = 4.5 V to 5.5 V	200	-	-	MHz	
C _{PD}	power dissipation capacitance	V _{CC} = 3.3 V	[3] [4] -	14	-	pF	
T_{amb} = -40 °C to +125 °C							
t _{PHL} , t _{PLH}	propagation delay CP to Q	see Figure 6					
		V _{CC} = 1.65 V to 1.95 V	1.5	-	17	ns	
		V _{CC} = 2.3 V to 2.7 V	1.0	-	9.0	ns	
		V _{CC} = 2.7 V	1.0	-	9.0	ns	
		V _{CC} = 3.0 V to 3.6 V	0.5	-	7.5	ns	
		V _{CC} = 4.5 V to 5.5 V	0.5	-	5.5	ns	
	propagation delay $\overline{\text{MR}}$ to Q	see Figure 7					
		V _{CC} = 1.65 V to 1.95 V	1.5	-	17	ns	
		V _{CC} = 2.3 V to 2.7 V	1.0	-	9.0	ns	
		V _{CC} = 2.7 V	1.0	-	9.0	ns	
		V _{CC} = 3.0 V to 3.6 V	0.5	-	7.5	ns	
		V _{CC} = 4.5 V to 5.5 V	0.5	-	5.5	ns	
t _w	clock pulse width HIGH or LOW	see Figure 6					
		V _{CC} = 1.65 V to 1.95 V	6.2	-	-	ns	
		V _{CC} = 2.3 V to 2.7 V	2.7	-	-	ns	
		V _{CC} = 2.7 V	2.7	-	-	ns	
		V _{CC} = 3.0 V to 3.6 V	2.7	-	-	ns	
		V _{CC} = 4.5 V to 5.5 V	2.0	-	-	ns	
	master reset pulse width LOW	see Figure 7					
		V _{CC} = 1.65 V to 1.95 V	6.2	-	-	ns	
		V _{CC} = 2.3 V to 2.7 V	2.7	-	-	ns	
		V _{CC} = 2.7 V	2.7	-	-	ns	
		V _{CC} = 3.0 V to 3.6 V	2.7	-	-	ns	
		V _{CC} = 4.5 V to 5.5 V	2.0	-	-	ns	

Table 8: Dynamic characteristics ...continuedGND = 0 V; see [Figure 8](#)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
t _{rem}	removal time master reset	see Figure 7				
		V _{CC} = 1.65 V to 1.95 V	1.9	-	-	ns
		V _{CC} = 2.3 V to 2.7 V	1.4	-	-	ns
		V _{CC} = 2.7 V	1.3	-	-	ns
		V _{CC} = 3.0 V to 3.6 V	1.2	-	-	ns
		V _{CC} = 4.5 V to 5.5 V	1.0	-	-	ns
t _{su}	set-up time D to CP	see Figure 6				
		V _{CC} = 1.65 V to 1.95 V	2.9	-	-	ns
		V _{CC} = 2.3 V to 2.7 V	1.7	-	-	ns
		V _{CC} = 2.7 V	1.7	-	-	ns
		V _{CC} = 3.0 V to 3.6 V	1.3	-	-	ns
		V _{CC} = 4.5 V to 5.5 V	1.1	-	-	ns
t _h	hold time D to CP	see Figure 6				
		V _{CC} = 1.65 V to 1.95 V	0.0	-	-	ns
		V _{CC} = 2.3 V to 2.7 V	0.3	-	-	ns
		V _{CC} = 2.7 V	0.5	-	-	ns
		V _{CC} = 3.0 V to 3.6 V	1.2	-	-	ns
		V _{CC} = 4.5 V to 5.5 V	0.5	-	-	ns
f _{max}	maximum clock pulse frequency	see Figure 6				
		V _{CC} = 1.65 V to 1.95 V	80	-	-	MHz
		V _{CC} = 2.3 V to 2.7 V	175	-	-	MHz
		V _{CC} = 2.7 V	175	-	-	MHz
		V _{CC} = 3.0 V to 3.6 V	175	-	-	MHz
		V _{CC} = 4.5 V to 5.5 V	200	-	-	MHz

- [1] All typical values are measured at T_{amb} = 25 °C.
- [2] These typical values are measured at V_{CC} = 3.3 V.
- [3] C_{PD} is used to determine the dynamic power dissipation (P_D in μW).
 $P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma(C_L \times V_{CC}^2 \times f_o)$ where:
 f_i = input frequency in MHz;
 f_o = output frequency in MHz;
 C_L = output load capacitance in pF;
 V_{CC} = supply voltage in Volts;
 N = number of inputs switching;
 $\Sigma(C_L \times V_{CC}^2 \times f_o)$ = sum of the outputs.
- [4] The condition is V_I = GND to V_{CC}.

12. Waveforms

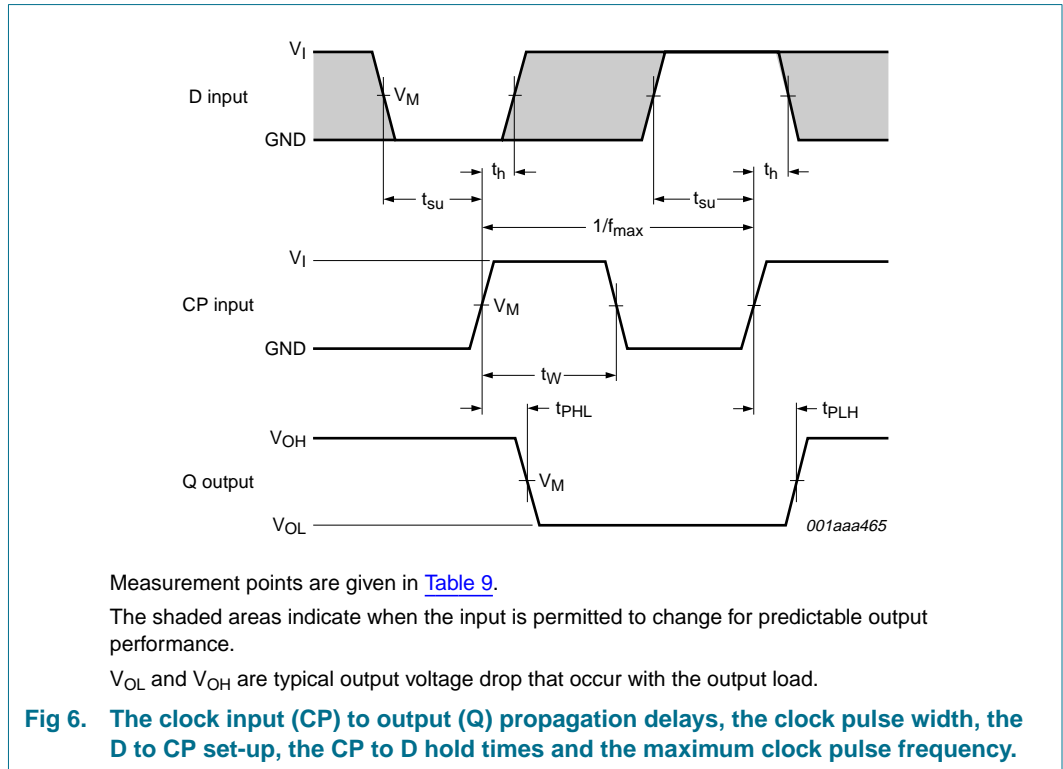
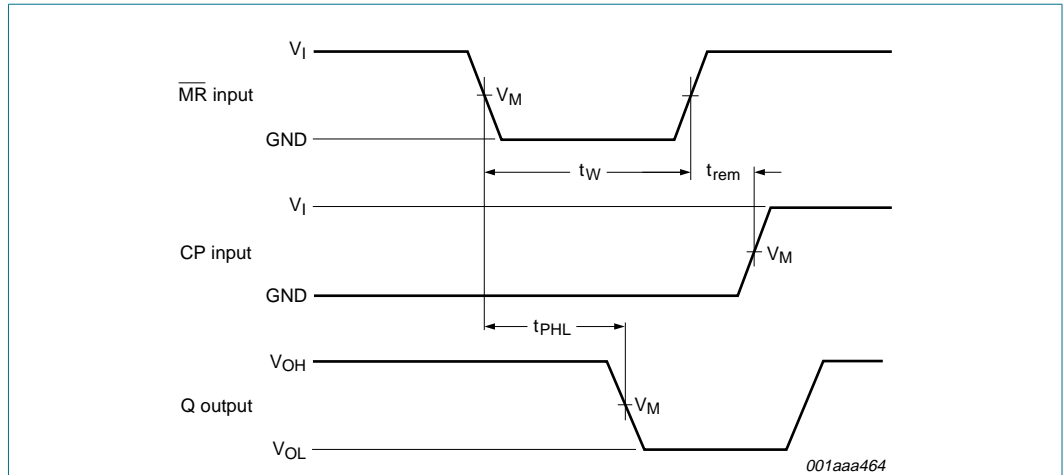


Table 9: Measurement points

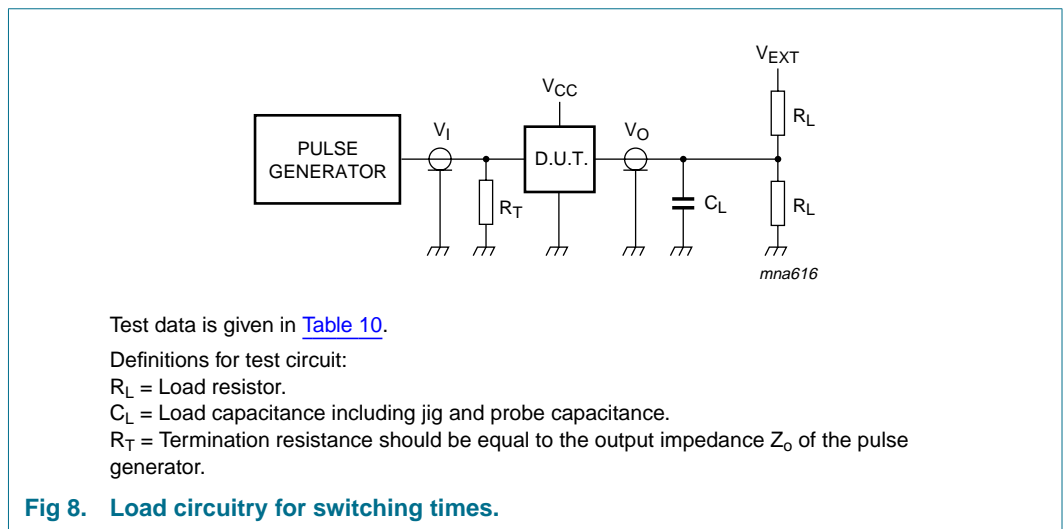
Supply voltage	Output	Input		
V_{CC}	V_M	V_M	V_I	$t_r = t_f$
1.65 V to 1.95 V	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$	V_{CC}	≤ 2.0 ns
2.3 V to 2.7 V	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$	V_{CC}	≤ 2.0 ns
2.7 V	1.5 V	1.5 V	2.7 V	≤ 2.5 ns
3.0 V to 3.6 V	1.5 V	1.5 V	2.7 V	≤ 2.5 ns
4.5 V to 5.5 V	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$	V_{CC}	≤ 2.5 ns



Measurement points are given in [Table 9](#).

V_{OL} and V_{OH} are typical output voltage drop that occur with the output load.

Fig 7. The master reset (\overline{MR}) input to output (Q) propagation delays, the master reset pulse width and the \overline{MR} to CP removal time.



Test data is given in [Table 10](#).

Definitions for test circuit:

R_L = Load resistor.

C_L = Load capacitance including jig and probe capacitance.

R_T = Termination resistance should be equal to the output impedance Z_o of the pulse generator.

Fig 8. Load circuitry for switching times.

Table 10: Test data

Supply voltage	Input	Load		V_{EXT}		
V_{CC}	V_I	C_L	R_L	t_{PLH} , t_{PHL}	t_{PZH} , t_{PHZ}	t_{PZL} , t_{PLZ}
1.65 V to 1.95 V	V_{CC}	30 pF	1 k Ω	open	GND	$2 \times V_{CC}$
2.3 V to 2.7 V	V_{CC}	30 pF	500 Ω	open	GND	$2 \times V_{CC}$
2.7 V	2.7 V	50 pF	500 Ω	open	GND	6 V
3.0 V to 3.6 V	2.7 V	50 pF	500 Ω	open	GND	6 V
4.5 V to 5.5 V	V_{CC}	50 pF	500 Ω	open	GND	$2 \times V_{CC}$

13. Package outline

Plastic surface mounted package; 6 leads

SOT363

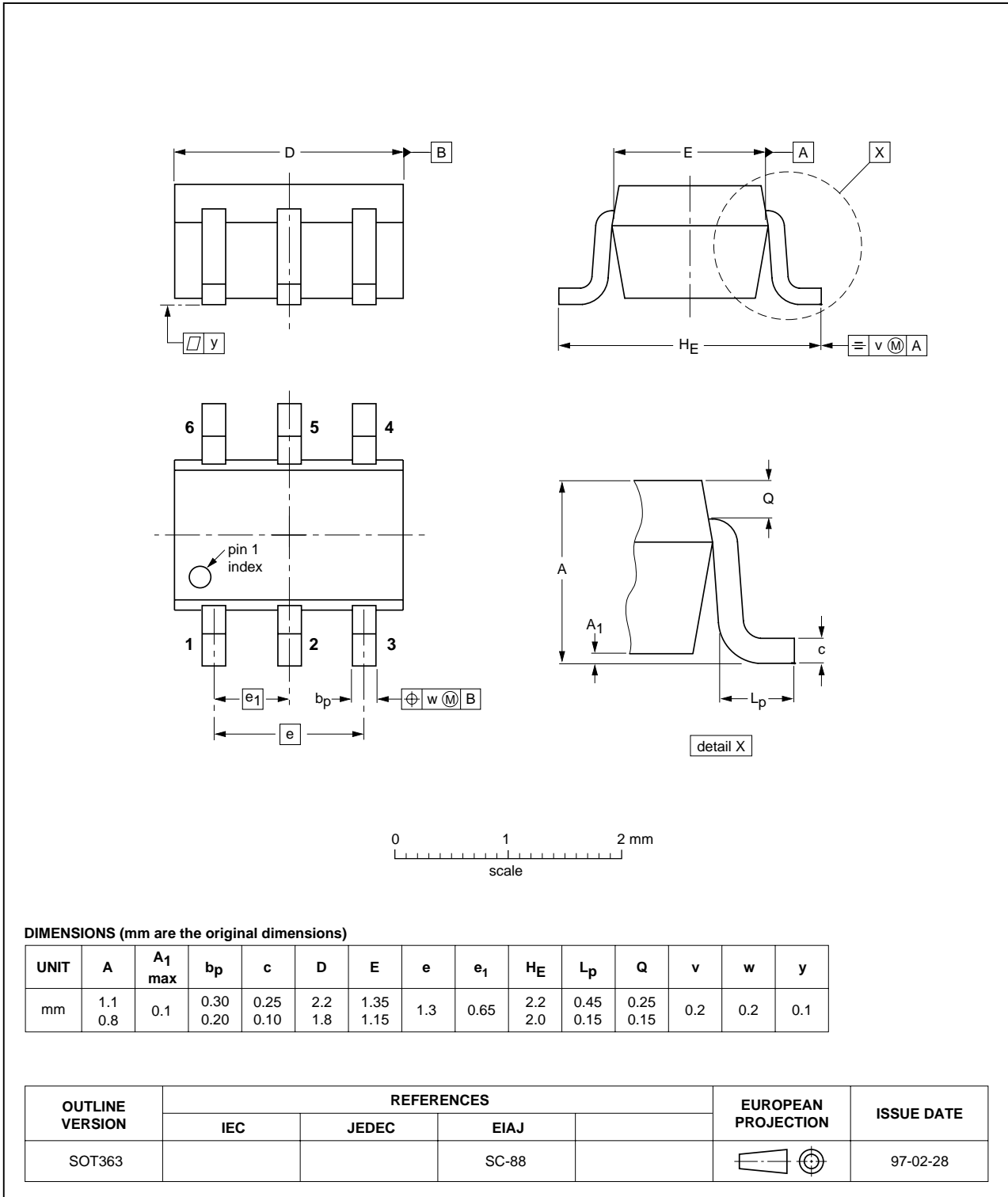


Fig 9. Package outline SOT363 (SC-88).

Plastic surface mounted package; 6 leads

SOT457

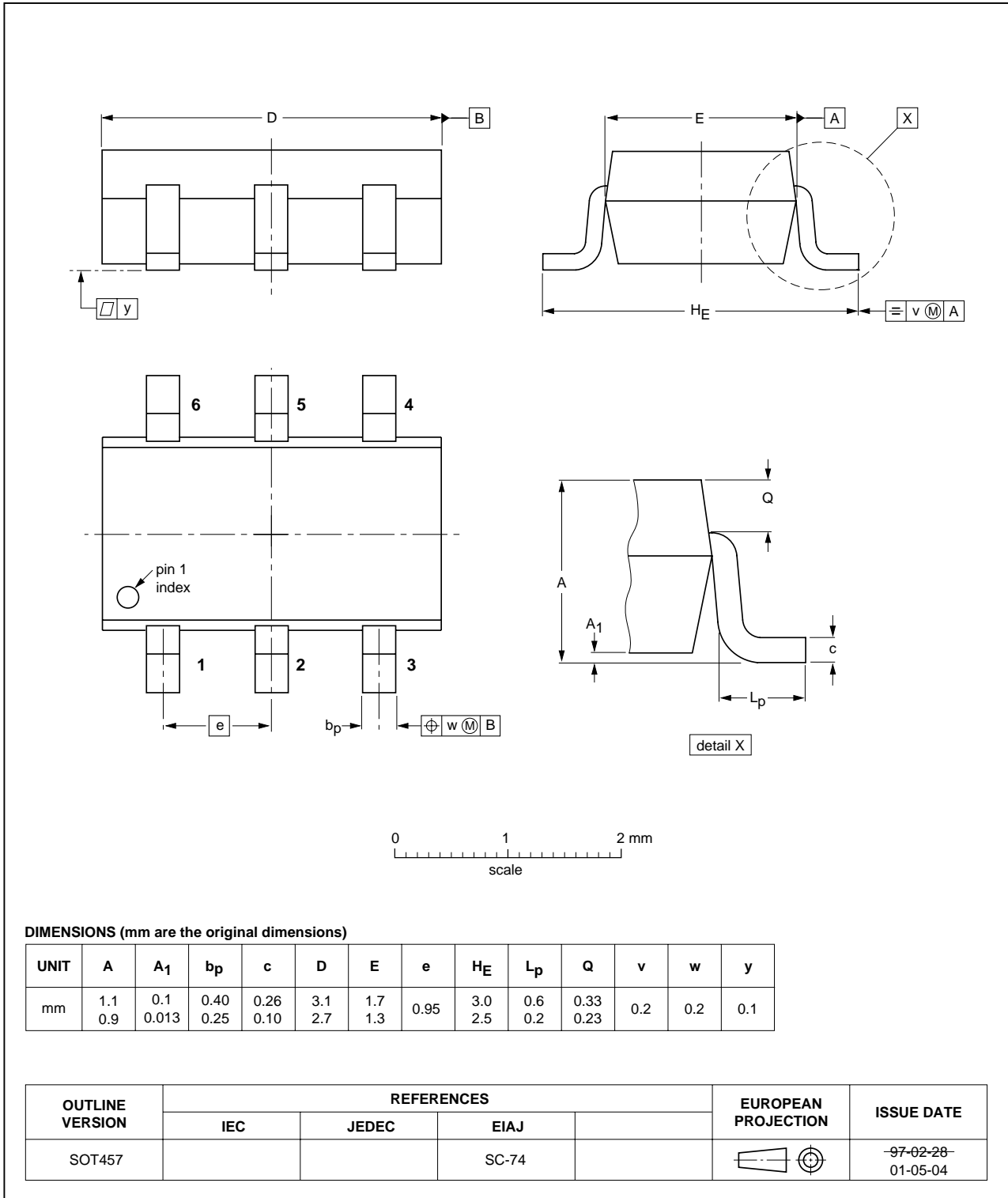
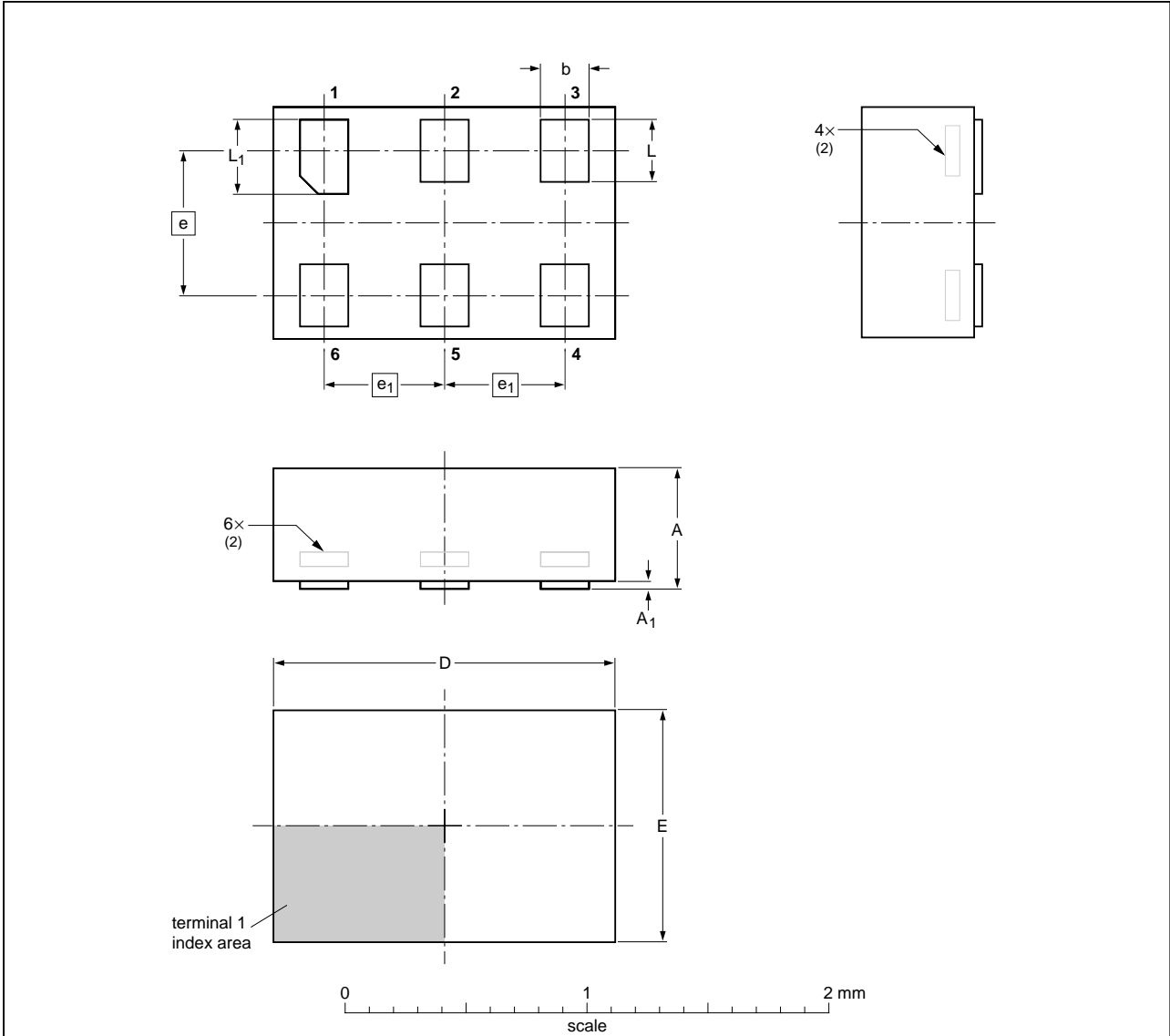


Fig 10. Package outline SOT457 (SC-74).

XSON6: plastic extremely thin small outline package; no leads; 6 terminals; body 1 x 1.45 x 0.5 mm

SOT886



DIMENSIONS (mm are the original dimensions)

UNIT	A ⁽¹⁾ max	A ₁ max	b	D	E	e	e ₁	L	L ₁
mm	0.5	0.04	0.25 0.17	1.5 1.4	1.05 0.95	0.6	0.5	0.35 0.27	0.40 0.32

Notes

- 1. Including plating thickness.
- 2. Can be visible in some manufacturing processes.

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
SOT886		MO-252			04-07-15 04-07-22

Fig 11. Package outline SOT886 (XSON6).

14. Revision history

Table 11: Revision history

Document ID	Release date	Data sheet status	Change notice	Doc. number	Supersedes
74LVC1G175_2	20041018	Product data sheet	-	9397 750 13762	74LVC1G175_1
Modifications	• Package outline. Marking code and ESD data added.				
74LVC1G175_1	20040318	Product data sheet	-	9397 750 12973	-

15. Data sheet status

Level	Data sheet status ^[1]	Product status ^[2] ^[3]	Definition
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
II	Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
III	Product data	Production	This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Relevant changes will be communicated via a Customer Product/Process Change Notification (CPCN).

[1] Please consult the most recently issued data sheet before initiating or completing a design.

[2] The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL <http://www.semiconductors.philips.com>.

[3] For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

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Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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Date of release: 18 October 2004
Document number: 9397 750 13762

Published in The Netherlands